Dexerials

Technical Data Sheet

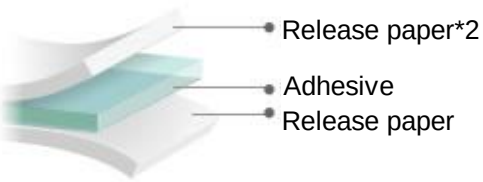
Adhesive transfer tapes for FPC & general-purpose

T4900/T4900W

Features

■ Ideal for bonding FPC materials such as Polyimide, Stainless steel plate (SUS304), Glass epoxy, etc.
■ Adhesive and release paper can resist high temperature of solder reflow process.
■ Low initial tackiness leads to high workability and excellent process ability.

Structure



Product name	T4900	T4900W *2
Main component	Acrylic	Acrylic
Carrier	Non-carrier	Non-carrier
Color	Translucent	Translucent
Adhesive thickness (μm)	About 50	About 50
Release paper thickness (μm)	About 90	About 90+130
Bonding strength (N/20mm) *3	9	9
St'd size (width & length)	500mm × 100m	500mm × 100m

* UL certificated. UL file No,（UL969 NO.MH15431）
*2 T4900W is with both side release paper
*3 180° peeling strength

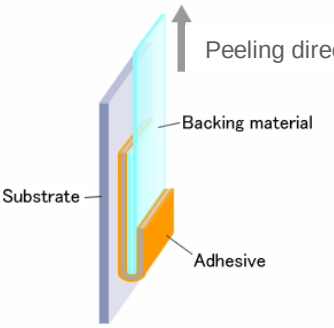
Suitable use

■ Ideal for bonding stiffener to FPC and bonding FPC for housing to electronic equipment.

Technical data

1. Bonding strength on various type of substrate (180° peeling)

＜Test piece condition＞
Tape width：20mm
Bonding condition：One stroke with 2-kg roller
Measuring condition：23℃±5℃ 60%±20%RH
Peeling speed：300mm/min
Backing material：25μmPET
[Left at RT for one hour before measurement]



＜180° peeling strength test＞

<Results>

（N/20mm）

Substrate	Poly-imide	Glass Epoxy	Stainless Steel	Aluminum	PET	ABS
Peeling strength	8	9	9	9	9	8

2. Bonding strength on various type of substrate after reflow (180° peeling)

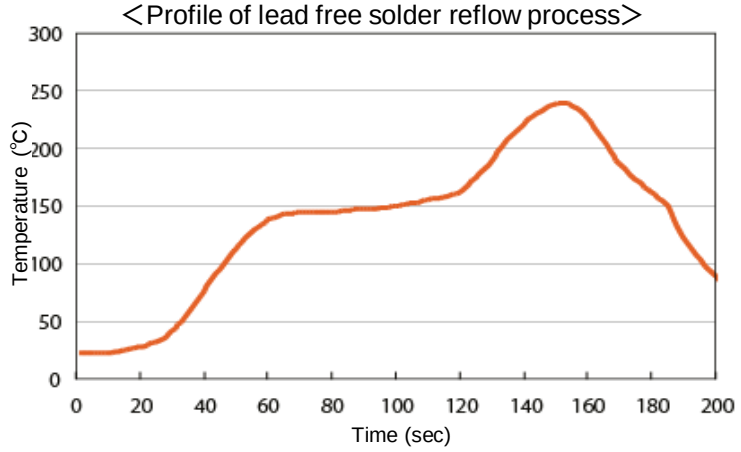
＜Test piece condition＞
Tape width: 20mm
Bonding condition: One stroke with 2-kg roller
Measuring condition: 23℃±5℃ 60%±20%RH
Peeling speed: 300mm/min
Backing material: 25μm Polyimide
[Attach adhesive tape to polyimide and reflow without removing release paper before measurement under the following conditions]

＜Results＞

(N/20mm)

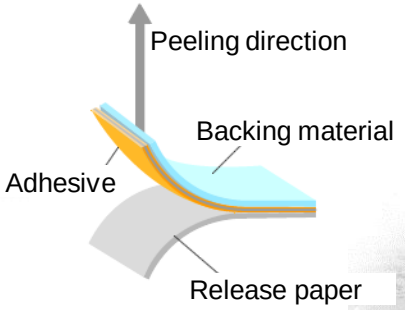
Substrate		Poly-Imide	Glass Epoxy	Stainless steel	Alumi num	PET	ABS
Peeling strength	Before reflow	8	9	9	9	9	8
	After reflow	9	9	9	9	9	8

＜Profile of lead free solder reflow process＞



3. Bonding strength of release paper before and after reflow

(T-peel strength and appearance of release paper)



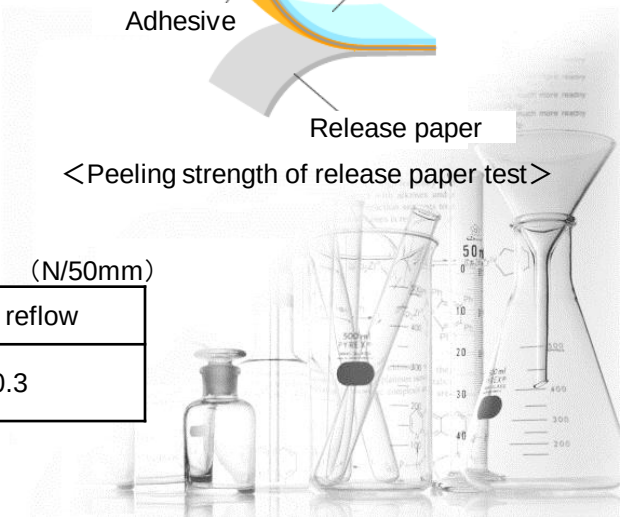
＜Peeling strength of release paper test＞

＜Test piece condition＞
Tape width: 50mm
Measuring condition: 23℃±5℃ 60%±20%RH
Peeling speed: 300mm/min
Backing material: 25μm Polyimide
[Reflow release paper/adhesive/polyimide film before measurement]

＜Results＞

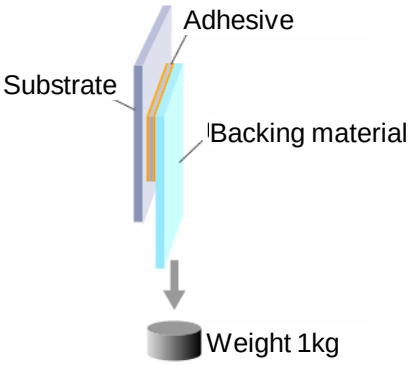
(N/50mm)

	Before reflow	After reflow
Release paper peeling strength	0.2	0.3



4. Holding power at different temperatures

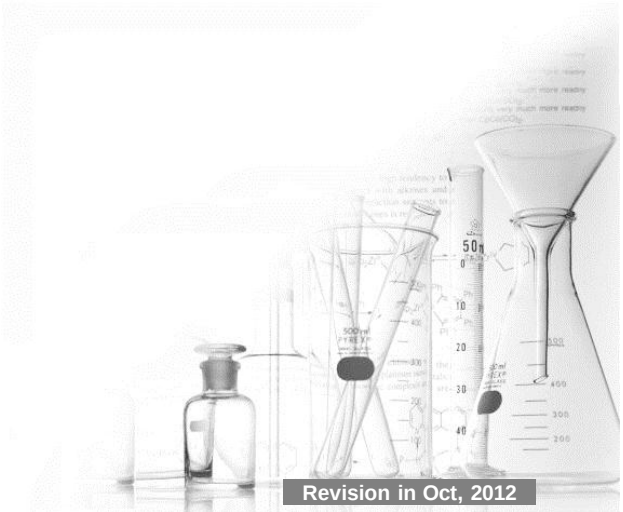
＜Test piece condition＞
Substrate: Stainless steel plate (SUS304)
Bonding area: 25mm × 25mm
Bonding condition: One stroke with 2-kg roller
Backing material: 25μm Polyimide
[Left at RT for one hour and then at each temperature for 30 minutes before measurement]
[Creep length after one hour application of 1-kg load]



＜Holding power test＞

＜Results＞ （mm）

Temperature	80℃	120℃
Creep length	0.2	0.3



Revision in Oct, 2012

Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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